

# NCE P-Channel Enhancement Mode Power MOSFET (Primary Version)

### Description

The NCE60P70D uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications.

#### **General Features**

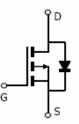
- V<sub>DS</sub> =-60V,I<sub>D</sub> =-70A
  - R<sub>DS(ON)</sub> <18mΩ @ V<sub>GS</sub>=-10V
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E<sub>AS</sub>
- Excellent package for good heat dissipation

#### Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

#### 100% UIS TESTED!

**100% ΔVds TESTED!** 



#### Schematic diagram



#### Marking and pin assignment



TO-263-2L top view

#### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE60P70D	NCE60P70D	TO-263-2L	-	-	-

### Absolute Maximum Ratings (T<sub>c</sub>=25<sup>°</sup>C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	Vds	-60	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	Ι <sub>D</sub>	-70	А
Drain Current-Continuous(T <sub>C</sub> =100℃)	I <sub>D</sub> (100℃)	-49.5	A
Pulsed Drain Current	I <sub>DM</sub>	280	A
Maximum Power Dissipation	PD	200	W
Derating factor		1.33	W/°C
Single pulse avalanche energy (Note 5)	E <sub>AS</sub>	TBD	mJ
Operating Junction and Storage Temperature Range	T <sub>J</sub> ,T <sub>STG</sub>	-55 To 175	°C
Thermal Characteristic			
Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	R <sub>θJC</sub>	0.75	°C/W



### Electrical Characteristics (T<sub>c</sub>=25<sup>°</sup>C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	· · ·					
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =-250µA	-60	-	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =-60V,V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20V, $V_{DS}$ =0V	-	-	±100	nA
On Characteristics (Note 3)	· · ·					
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS}$ , $I_{D}=-250\mu A$	-1.0	-1.75	-2.5	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> =-20A	-	15.5	18	mΩ
Forward Transconductance	<b>g</b> fs	V <sub>DS</sub> =-5V,I <sub>D</sub> =-20A	-	TBD	-	S
Dynamic Characteristics (Note4)	· · ·					
Input Capacitance	C <sub>lss</sub>		-	3850	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =-30V,V <sub>GS</sub> =0V, F=1.0MHz	-	249	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	194	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =-30V,I <sub>D</sub> =-20A V <sub>GS</sub> =-10V,R <sub>GEN</sub> =3Ω	-	TBD	-	nS
Turn-on Rise Time	tr		-	TBD	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	TBD	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	TBD	-	nS
Total Gate Charge	Qg	V <sub>DS</sub> =-30V,I <sub>D</sub> =-20A, V <sub>GS</sub> =-10V	-	73	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	14	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	VGS10V	-	18	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =-20A	-	-	1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	-70	А
Reverse Recovery Time	trr	TJ = 25°C, IF = -20A	-	TBD	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/µs <sup>(Note3)</sup>	-	TBD	-	nC

#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

**2.** Surface Mounted on FR4 Board,  $t \le 10$  sec.

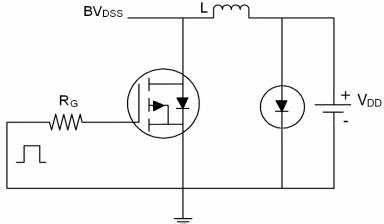
**3.** Pulse Test: Pulse Width  $\leq$  300µs, Duty Cycle  $\leq$  2%.

4. Guaranteed by design, not subject to production

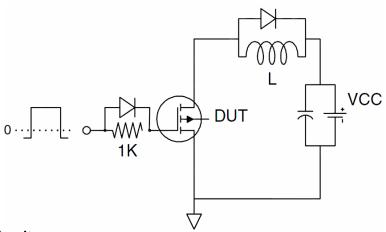
5. EAS condition: Tj=25 $^\circ\!\!\mathrm{C}$ ,V\_DD=-30V,VG=-10V,L=0.5mH,Rg=25 $\Omega$ 



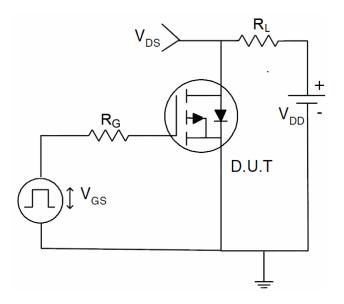
## Test Circuit 1) E<sub>AS</sub> Test Circuit



## 2) Gate Charge Test Circuit

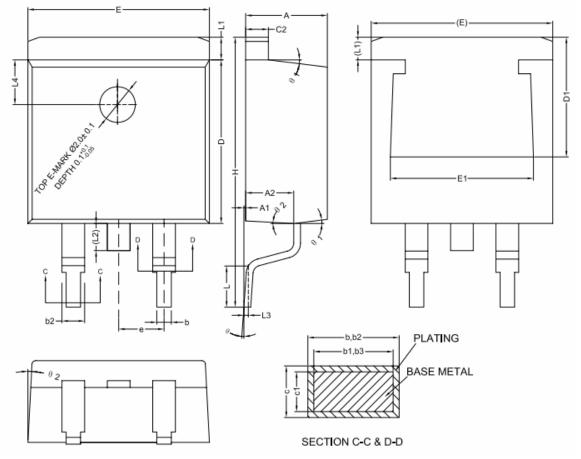


3) Switch Time Test Circuit





## **TO-263-2L Package Information**



COMMON DIMENSIONS (UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX	
A	4.40	4.57	4.70	
A1	0	0.10	0.25	
A2	2.59	2.69	2.79	
b	0.77	-	0.90	
b1	0.76	0.81	0.86	
b2	1.23	-	1.36	
b3	1.22	1.27	1.32	
с	0.34	-	0.47	
c1	0.33	0.38	0.43	
c2	1.22	-	1.32	
D	9.05	9.15	9.25	
D1	6.60	-	-	
E	10.06	10.16	10.26	
E1	7.80	-	8.20	
е	2.54BSC			
Н	14.70	15.10	15.50	
L	2.00	2.30	2.60	
L1	1.17	1.27	1.40	
L2	-	-	1.75	
L3	0.25BSC			
L4	2.00REF			
θ	0°	-	8°	
θ 1	5°	7°	9°	
θ2	1°	3°	5°	



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